



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP100N10S3-05	Issued	11. May 2021
MA#	MA001663184		
Package	PG-TO220-3-1	Weight*	2045.04 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.369	0.75	0.75	7515	7515
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		399	
	non noble metal	copper	7440-50-8	815.335	39.87	39.92	398689	399208
wire	non noble metal	aluminium	7429-90-5	10.758	0.53	0.53	5260	5260
encapsulation	inorganic material	zinc oxide	1314-13-2	5.812	0.28		2842	
	miscellaneous	miscellaneous	-	23.247	1.14		11368	
	plastics	epoxy resin	-	87.176	4.26		42628	
	inorganic material	silicon dioxide	60676-86-0	464.940	22.74	28.42	227350	284188
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10495	10495
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	119	120
solder	non noble metal	tin	7440-31-5	0.188	0.01		92	
	noble metal	silver	7440-22-4	0.235	0.01		115	
	non noble metal	lead	7439-92-1	8.975	0.44	0.46	4389	4596
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.82	28.86	288242	288618
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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